



COPY OF PAPERS
ORIGINALLY FILED

IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

In re ~~Application~~ of:

Yamakawa, et al.

: Examiner: Graybill, D.

Title: Adhesive and Semiconductor
Devices

: Reply to Election of Species Requirement

: Art Unit: 2827

Serial No.: 09/597,218

: Confirmation No.: 5276

Filed: 20 June, 2000

:

Docket No.: TSL 1549

: Date: 22 April, 2002

Assistant Commissioner for Patents
Washington, DC 20231

TECHNOLOGY CENTER 2800

MAY - 7 2002

RECEIVED

#12A
5/17/02

Sir:

In response to the Office Action dated 27 March 2002, the applicants request reconsideration based on the following amendments and remarks.

AMENDMENTS

Please replace pending claim 10 with amended claim 10.

81 10. (amended) A semiconductor device comprising a semiconductor chip bonded to an attachment member for the chip by an adhesive composition comprising a curable polymer composition comprising from 1 to 900 weight-ppm spherical filler having an average particle size of from 10 to 100 μm and a major axis-to-minor axis ratio of from 1 to 1.5.

REMARKS

The Examiner withdrew the election requirement dated 30 October 2001. Claims 1-17 are pending in the application. Claim 10 has been amended. The amendments do not add new matter to the claims

The Examiner rejected claims 12, 14, 15, and 17 under 35 U.S.C. § 112, second paragraph, as being indefinite for failing to particularly point out and distinctly claim the subject matter which the Applicants regard as their invention because there is insufficient literal antecedent basis for the term, "the curable polymer composition".

Claim 10 has been amended to include the curable polymer composition. Claims 12, 14, 15, and 17 are dependent on claim 10. Support for the amendment to claim 10 can be found at p. 3, line